



[10191/3935]

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Inventor(s) : LAERMER ET AL.  
Filed : January 05, 2005  
Serial No. : 10/506,457  
For : DEVICE AND METHOD FOR ANISOTROPIC  
PLASMA ETCHING OF A SUBSTRATE,  
A SILICON BODY IN PARTICULAR  
Examiner : Allan W. Olsen  
Art Unit : 1763  
Confirmation No. : 9990

Address to:

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on:

Date: August 15, 2006

Signature: Ch. H. H.

**AMENDMENT**

SIR:

In response to the Office Action dated March 30, 2006 please amend the above-captioned application without prejudice as follows:

**Amendments to the Drawings** begin on page 2 of this paper.

**Remarks** begin on page 3 of this paper.

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